FAIRCHILD SEMICONDUCTOR®

February 2008

74VCX08
Low Voltage Quad 2-Input AND Gate with 3.6V Tolerant Inputs and Outputs

Features

- 1.2V to 3.6V V_{CC} supply operation
- 3.6V tolerant inputs and outputs
- t_{PD}:
  - 2.8ns max. for 3.0V to 3.6V V_{CC}
- Power-off high impedance inputs and outputs
- Static Drive (I_{OH}/I_{OL})
  - ±24mA @ 3.0V V_{CC}
- Uses proprietary Quiet Series™ noise/EMI reduction circuitry
- Latchup performance exceeds 300mA
- ESD performance:
  - Human body model > 2000V
  - Machine model > 250V
- Leadless DQFN package

General Description

The VCX08 contains four 2-input AND gates. This product is designed for low voltage (1.2V to 3.6V) V_{CC} applications with I/O compatibility up to 3.6V.

The VCX08 is fabricated with an advanced CMOS technology to achieve high-speed operation while maintaining low CMOS power dissipation.

Ordering Information

Order Number	Package Number	Package Description
74VCX08M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74VCX08BQX(1)	MLP14A	14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm
74VCX08MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Note:

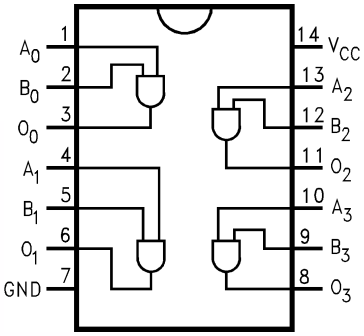
1. DQFN package available in Tape and Reel only.

Device also available in Tape and Reel. Specify by appending suffix letter “X” to the ordering number.

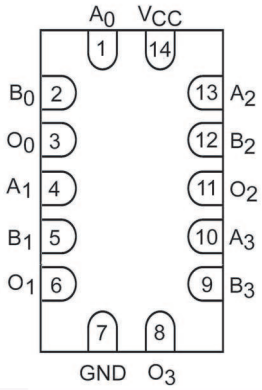
All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagrams

Pin Assignments for SOIC and TSSOP



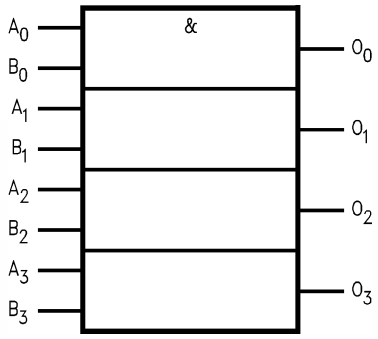
Pad Assignments for DQFN



(Top View)

Logic Symbol

IEEE/IEC



Pin Description

Pin Names	Description
A_n, B_n	Inputs
O_n	Outputs

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	–0.5V to +4.6V
V_I	DC Input Voltage	–0.5V to 4.6V
V_O	DC Output Voltage	
	HIGH or LOW State(2)	–0.5V to V_{CC}+0.5V
	V_{CC} = 0V	–0.5V to +4.6V
I_{IK}	DC Input Diode Current, V_I < 0V	–50mA
I_{OK}	DC Output Diode Current	
	V_O < 0V	–50mA
	V_O > V_{CC}	+50mA
I_{OH} / I_{OL}	DC Output Source/Sink Current	+50mA
I_{CC} or GND	DC V_{CC} or Gound Current per Supply Pin	±100mA
T_{STG}	Storage Temperature Range	–65°C to +150°C

Note:

2. I_O Absolute Maximum Rating must be observed.

Recommended Operating Conditions(3)

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V_{CC}	Power Supply Operating	1.2V to 3.6V
V_I	Input Voltage	–0.3V to 3.6V
V_O	Output Voltage, HIGH or LOW State	0V to V_{CC}
I_{OH} / I_{OL}	Output Current	
	V_{CC} = 3.0V to 3.6V	±24mA
	V_{CC} = 2.3V to 2.7V	±18mA
	V_{CC} = 1.65V to 2.3V	±6mA
	V_{CC} = 1.4V to 1.6V	±2mA
	V_{CC} = 1.2V	±100µA
T_A	Free Air Operating Temperature	–40°C to +85°C
$\Delta t / \Delta V$	Minimum Input Edge Rate, V_{IN} = 0.8V to 2.0V, V_{CC} = 3.0V	10ns/V

Note:

3. Floating or unused inputs must be held HIGH or LOW

DC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	Conditions	Min	Max	Units
V_{IH}	HIGH Level Input Voltage	2.7–3.6		2.0		V
		2.3–2.7		1.6		
		1.65–2.3		$0.65 \times V_{CC}$		
		1.4–1.6		$0.65 \times V_{CC}$		
		1.2		$0.65 \times V_{CC}$		
V_{IL}	LOW Level Input Voltage	2.7–3.6			0.8	V
		2.3–2.7			0.7	
		1.65–2.3			$0.35 \times V_{CC}$	
		1.4–1.6			$0.35 \times V_{CC}$	
		1.2			$0.05 \times V_{CC}$	
V_{OH}	HIGH Level Output Voltage	2.7–3.6	$I_{OH} = -100\mu A$	$V_{CC} - 0.2$		V
		2.7	$I_{OH} = -12mA$	2.2		
		3.0	$I_{OH} = -18mA$	2.4		
		3.0	$I_{OH} = -24mA$	2.2		
		2.3–2.7	$I_{OH} = -100\mu A$	$V_{CC} - 0.2$		
		2.3	$I_{OH} = -6mA$	2.0		
		2.3	$I_{OH} = -12mA$	1.8		
		2.3	$I_{OH} = -18mA$	1.7		
		1.65–2.3	$I_{OH} = -100\mu A$	$V_{CC} - 0.2$		
		1.65	$I_{OH} = -6mA$	1.25		
		1.4–1.6	$I_{OH} = -100\mu A$	$V_{CC} - 0.2$		
		1.4	$I_{OH} = -2mA$	1.05		
		1.2	$I_{OH} = -100\mu A$	$V_{CC} - 0.2$		
V_{OL}	LOW Level Output Voltage	2.7–3.6	$I_{OL} = 100\mu A$		0.2	V
		2.7	$I_{OL} = 12mA$		0.4	
		3.0	$I_{OL} = 18mA$		0.4	
		3.0	$I_{OL} = 24mA$		0.55	
		2.3–2.7	$I_{OL} = 100\mu A$		0.2	
		2.3	$I_{OL} = 12mA$		0.4	
		2.3	$I_{OL} = 18mA$		0.6	
		1.65–2.3	$I_{OL} = 100\mu A$		0.2	
		1.65	$I_{OL} = 6mA$		0.2	
		1.4–1.6	$I_{OL} = 100\mu A$		0.2	
		1.4	$I_{OL} = 2mA$		0.35	
		1.2	$I_{OL} = 100\mu A$		0.05	
I_I	Input Leakage Current	1.2–3.6	$0 \le V_I \le 3.6V$		±5.0	µA
I_{OFF}	Power-OFF Leakage Current	0	$0 \le (V_I, V_O) \le 3.6V$		10	µA
I_{CC}	Quiescent Supply Current	1.2–3.6	$V_I = V_{CC}$ or GND		20	µA
			$V_{CC} \le V_I \le 3.6V$		±20	
ΔI_{CC}	Increase in I_{CC} per Input	2.7–3.6	$V_{IH} = V_{CC} - 0.6V$		750	µA

AC Electrical Characteristics[4]

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = –40°C to +85°C		Units	Figure Number
				Min.	Max.		
t_{PHL}, t_{PLH}	Propagation Delay	3.3 ± 0.3	C_L = 30pF, R_L = 500Ω	0.6	2.8	ns	Fig. 1
		2.5 ± 0.2		0.8	3.7		Fig. 2
		1.8 ± 0.15		1.0	7.4		
		1.5 ± 0.1	C_L = 15pF, R_L = 2kΩ	1.0	14.8		Fig. 3
		1.2		1.5	37.0		Fig. 4
t_{OSHL}, t_{OSLH}	Output to Output Skew[5]	3.3 ± 0.3	C_L = 30pF, R_L = 500Ω		0.5	ns	
		2.5 ± 0.2			0.5		
		1.8 ± 0.15			0.75		
		1.5 ± 0.1	C_L = 15pF, R_L = 2kΩ		1.5		
		1.2			1.5		

Note:

4. For C_L = 50pF, add approximately 300ps to the AC Maximum specification.
5. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

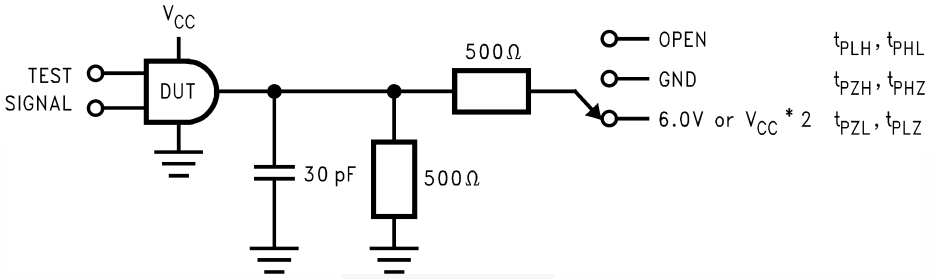
Dynamic Switching Characteristics

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = 25°C	Unit
				Typical	
V_{OLP}	Quiet Output Dynamic Peak V_{OL}	1.8	C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V	0.25	V
		2.5		0.6	
		3.3		0.8	
V_{OLV}	Quiet Output Dynamic Valley V_{OL}	1.8	C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V	–0.25	V
		2.5		–0.6	
		3.3		–0.8	
V_{OHV}	Quiet Output Dynamic Valley V_{OH}	1.8	C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V	1.5	V
		2.5		1.9	
		3.3		2.2	

Capacitance

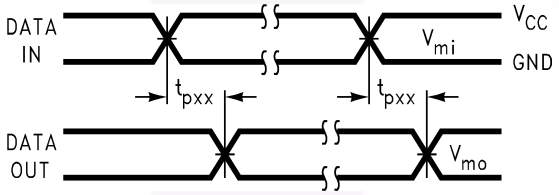
Symbol	Parameter	Conditions	T_A = +25°C	Units
			Typical	
C_{IN}	Input Capacitance	V_I = 0V or V_{CC}, V_{CC} = 1.8V, 2.5V or 3.3V	6.0	pF
C_{OUT}	Output Capacitance	V_I = 0V or V_{CC}, V_{CC} = 1.8V, 2.5V or 3.3V	7.0	pF
C_{PD}	Power Dissipation Capacitance	V_I = 0V or V_{CC}, f = 10MHz, V_{CC} = 1.8V, 2.5V or 3.3V	20.0	pF

AC Loading and Waveforms (V_{CC} 3.3V ± 0.3V to 1.8V ± 0.15V)



Test	Switch
t_{PLH}, t_{PHL}	Open

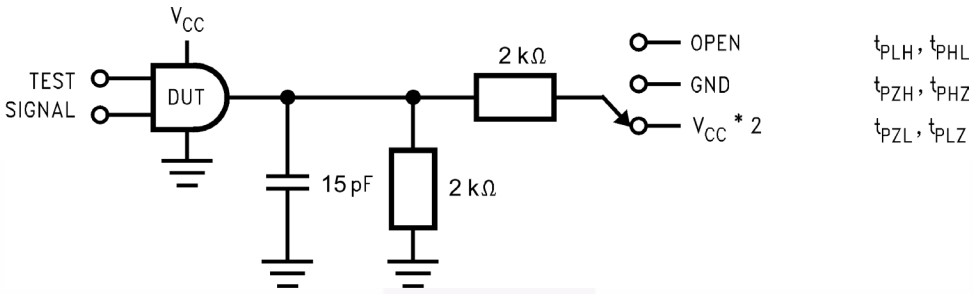
Figure 1. AC Test Circuit



Symbol	V_{CC}		
	3.3V ± 0.3V	2.5V ± 0.2V	1.8V ± 0.15V
V_{mi}	1.5V	V_{CC} / 2	V_{CC} / 2
V_{mo}	1.5V	V_{CC} / 2	V_{CC} / 2

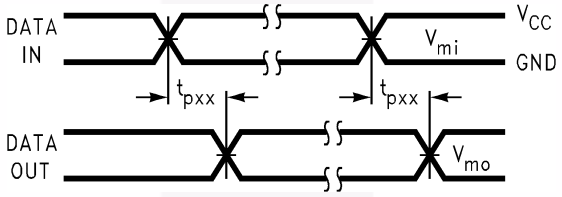
Figure 2. Waveform for Inverting and Non-inverting Functions

AC Loading and Waveforms (V_{CC} 1.5 ± 0.1V to 1.2V)



Test	Switch
t_{PLH}, t_{PHL}	Open
t_{PZL}, t_{PLZ}	V_{CC} x 2 at V_{CC} = 1.5V ± 0.1V
t_{PZH}, t_{PHZ}	GND

Figure 3. AC Test Circuit



Symbol	V_{CC}
	1.5V ± 0.1V
V_{mi}	V_{CC} / 2
V_{mo}	V_{CC} / 2

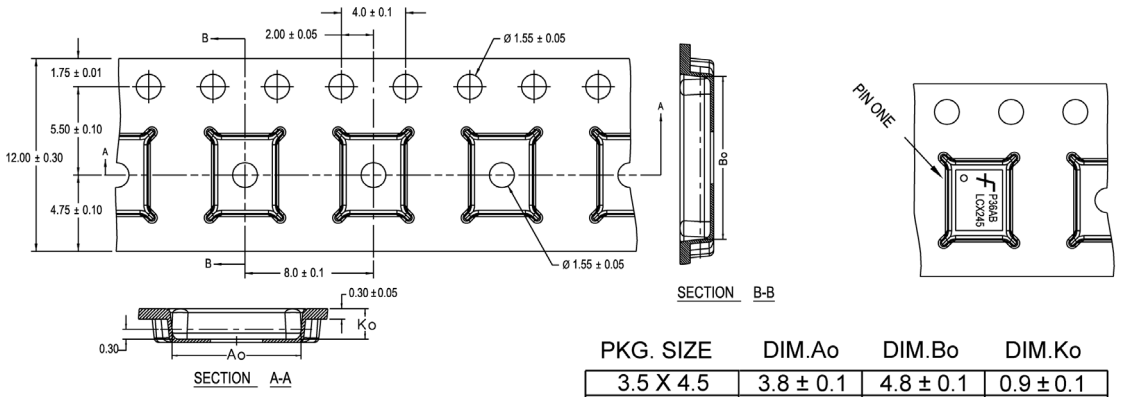
Figure 4. Waveform for Inverting and Non-Inverting Functions

Tape and Reel Specification

Tape Format for DQFN

Package Designator	Tape Section	Number of Cavities	Cavity Status	Cover Tape Status
BQX	Leader (Start End)	125 (Typ.)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (Typ.)	Empty	Sealed

Tape Dimensions inches (millimeters)



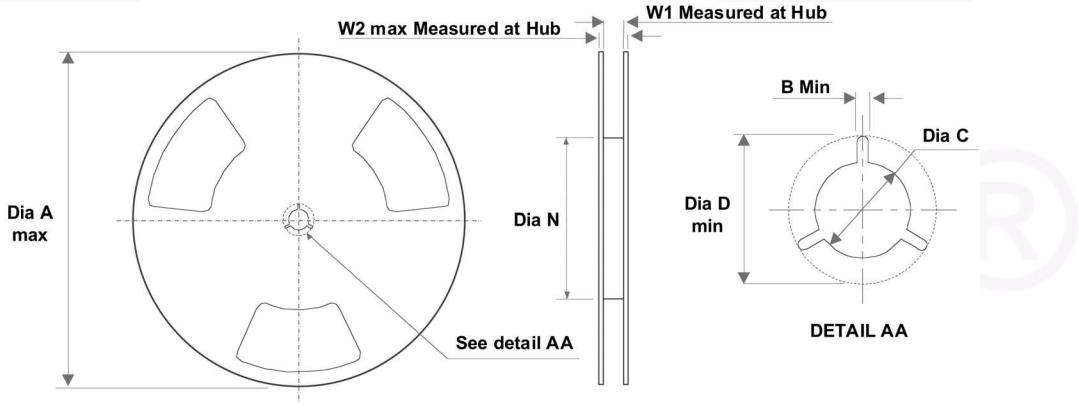
PKG. SIZE	DIM.Ao	DIM.Bo	DIM.Ko
3.5 X 4.5	3.8 ± 0.1	4.8 ± 0.1	0.9 ± 0.1
3.0 X 3.0	3.3 ± 0.1	3.3 ± 0.1	0.9 ± 0.1
2.5 X 4.5	2.8 ± 0.1	4.8 ± 0.1	0.9 ± 0.1
2.5 X 3.5	2.8 ± 0.1	3.8 ± 0.1	0.9 ± 0.1
2.5 X 3.0	2.8 ± 0.1	3.3 ± 0.1	0.9 ± 0.1
2.5 X 2.5	2.8 ± 0.1	2.8 ± 0.1	0.9 ± 0.1

DIMENSIONS ARE IN MILLIMETERS

NOTES: unless otherwise specified

1. Cummulative pitch for feeding holes and cavities (chip pockets) not to exceed 0.008[0.20] over 10 pitch span.
2. Smallest allowable bending radius.
3. Thru hole inside cavity is centered within cavity.
4. Tolerance is ±0.002[0.05] for these dimensions on all 12mm tapes.
5. Ao and Bo measured on a plane 0.120[0.30] above the bottom of the pocket.
6. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
7. Pocket position relative to sprocket hole measured as true position of pocket. Not pocket hole.
8. Controlling dimension is millimeter. Diemension in inches rounded.

Reel Dimensions inches (millimeters)



Tape Size	A	B	C	D	N	W1	W2
12mm	13.0 (330.0)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	2.165 (55.00)	0.488 (12.4)	0.724 (18.4)

Physical Dimensions

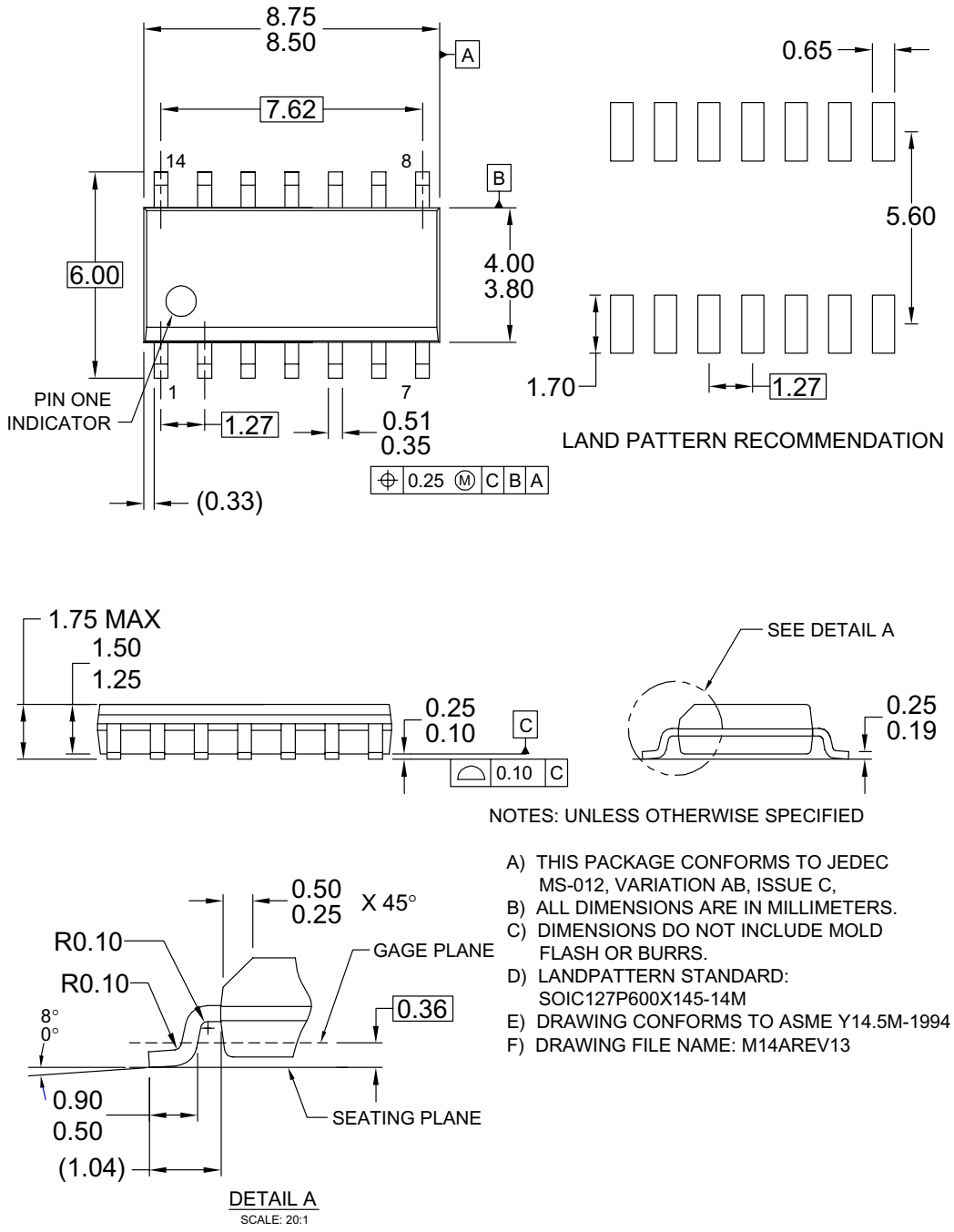


Figure 5. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

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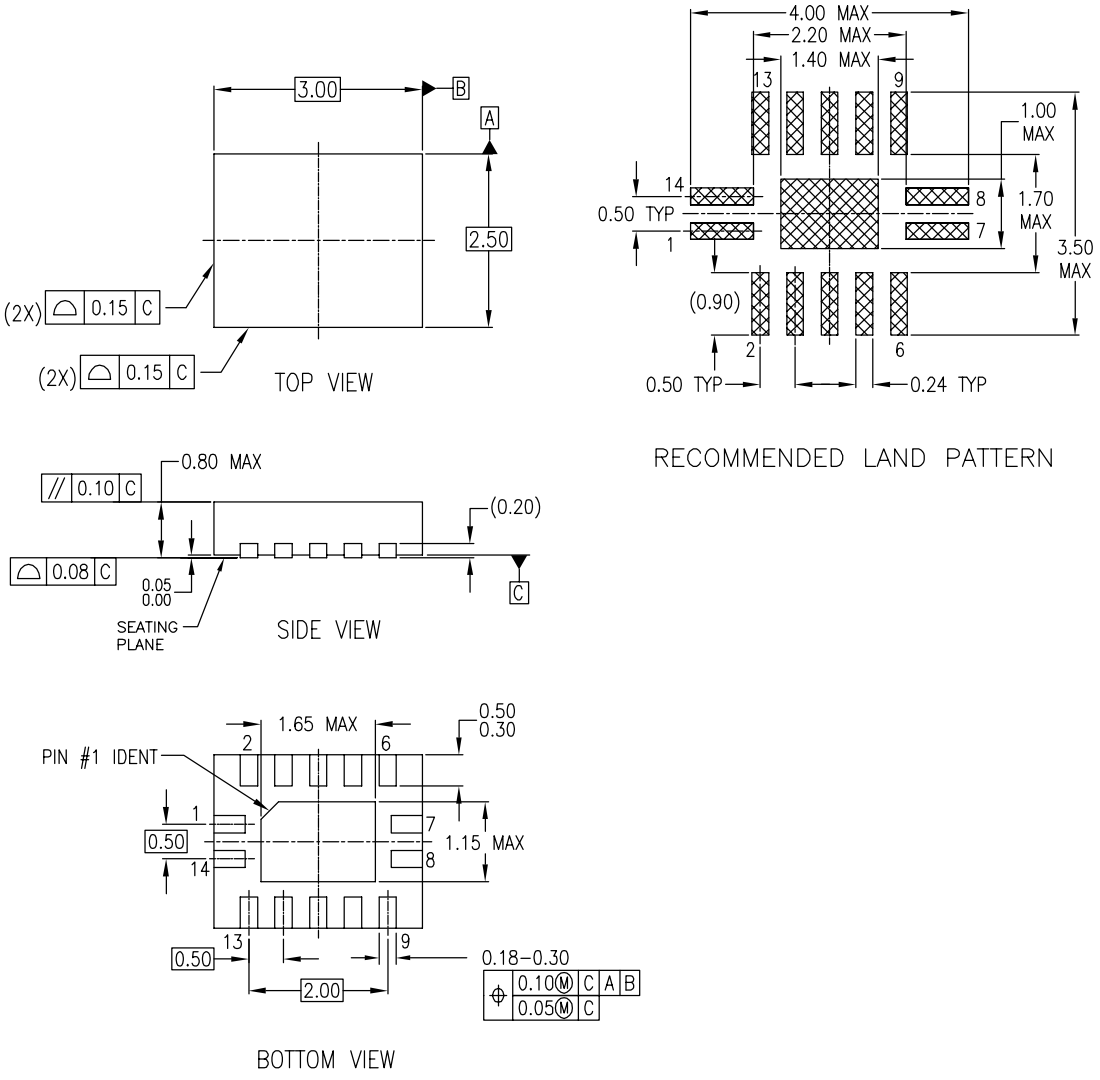
Physical Dimensions (Continued)



NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO–241, VARIATION AA

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP14ArevA

Figure 6. 14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm

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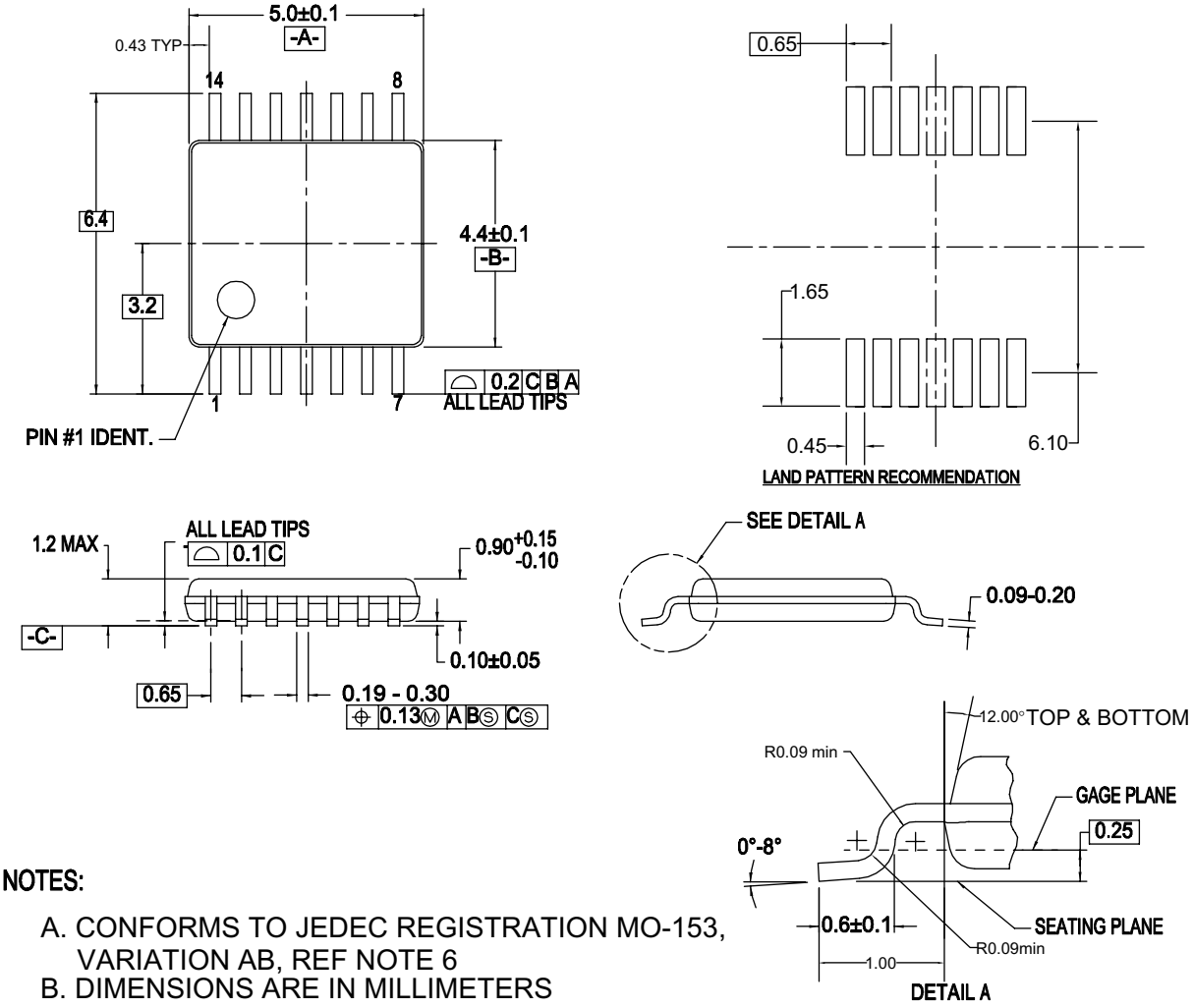
Physical Dimensions (Continued)



NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6

B. DIMENSIONS ARE IN MILLIMETERS

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS

D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982

E. LANDPATTERN STANDARD: SOP65P640X110-14M

F. DRAWING FILE NAME: MTC14REV6

Figure 7. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild Semiconductor. The datasheet is printed for reference information only.

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